

- 5.Storage temperature:-30°C~+80°C
- 6.Driver IC:ST7272A

## **PRODUCT SPECIFICATION**

# 3.5" TFT LCD MODULEMODEL:YDP LCD | 350 SRVer:1.1

- $< \diamond >$  Preliminary Specification
- < <> Finally Specification

	CUSTOMER'S APPROVAL						
CUSTOMER :	CUSTOMER :						
SIGNATURE: DATE:							

APPROVED	РМ	PD	PREPARED
BY	REVIEWED	REVIEWED	BY
TFT S. G. H 20220905			TFT L.Q 20220905

## **Revision History**

Revision	Date	Originator	Detail	Remarks
1.0	2021.04.15	ZJW	Initial Release	
1.1	2022.09.05	LQ	Add Weight Add CIE Value	P4 P6

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## 1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

## 2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	3.5"	
LCD type	IPS TFT	
Display Mode	Transmissive /Normally black	
Resolution	320 RGB x 240	Pixels
View Direction	FULL VIEW	Best Image
Module Outline	76.9(H) x 63.9(V) x 3.2(T) (Note1)	mm
Active Area	70.08(H) x 52.56(V)	mm
Pixel Size	219(H) x219(V)	um
Pixel Arrangement	RGB stripe	
Polarizer Surface Treatment	Anti-glare	
Display Colors	16.7M	
Interface	24-bit RGB Interface+3 wire SPI	
Driver IC	ST7272A	-
With or Without Touch Panel	Without	
Operating Temperature	-20~70	°C
Storage Temperature	-30~80	°C
Weight	30	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

## 3. Absolute Maximum Ratings

Vss=0V, Ta=25°C

			+55 €	, ia 20 0
ltem	Symbol	Min.	Max.	Unit
Supply Voltage	VDD	-0.3	4.0	V
Storage temperature	Tstg	-30	+80	°C
Operating temperature	Тор	-20	+70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

## 4. DC Characteristics

Item		Symbol	Min.	Тур.	Max.	Unit
Supply Voltage		VDD	3.0	3.3	3.6	V
Logic Low input voltage		VIL	GND	-	0.3*VDD	V
Logic High input voltage		Vін	0.7*VDD	-	VDD	V
Logic Low output voltage		Vol	GND	-	GND+0.4	V
Logic High output voltage		V <sub>он</sub>	VDD-0.4	-	VDD	V
Current Consumption Logic		laa luu		(24)		mA
All White	Analog	Icc+ lin	-	(24)	-	ША

## 5. Backlight Characteristic

#### 5.1. Backlight Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	Vf	Ta=25 °C, IF=20mA/LED	17.4	18.6	19.8	V
Forward Current	İF	Ta=25 °C, VF=3.1V/LED	(30)	40	(50)	mA
Power dissipation	Pd		-	744	-	mW
LED Life Time(25 °C)	-	-	(20,000)	-	-	Hr
Uniformity	Avg		80	85	-	%
Drive method	Constant current					
LED Configuration	12 \	White LEDs (6 LEDs in one	string and	2 groups	s in paral	lel)

Note: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25±2 °C,60%RH±5%.

#### 5.2. Backlighting circuit



## 6. Optical Characteristics

#### 6.1. Optical Characteristics

Ta=25°C,  $V_{DD}$ =3.3V

	14.0.1		Symphol	Condition	S	pecificati	on	L Incid
	Iter	ltem		Symbol Condition		Тур.	Max.	Unit
	Luminar	nce on						
	TFT( $I_f$ =20	)mA/LED)	Lv	Normally	800	1000	-	cd/m²
Mode)	Contrast rati	o(See 6.3)	CR	viewing angle	640	800	-	
			Tr	θx = φy =0°		25	35	ma
On (Transmissive			TF		-	29	30	ms
nis		Red	Xr		0.577	0.627	0.677	
Inst		Green	Yr		0.304	0.354	0.404	
Tra	Chromoticity		Xg		0.281	0.331	0.381	
<u>ج</u>	Chromaticity Transmissive	Gleen	Yg		0.542	0.592	0.642	
Ĕ	(See 6.5)	Blue	Хв		0.082	0.132	0.182	
Backlight	(000 0.0)	Dide	Υв		0.014	0.064	0.114	
ack		White	Xw		0.268	0.318	0.368	
m l		VVIIILE	Yw		0.293	0.343	0.393	
	Viewing	Horizontal	θx+		70	80	-	
	Viewing Horizonta Angle	nonzoniai	Өх-	Center CR≥10	70	80	-	Deg.
	(See 6.4)	Vertical	φΥ+		70	80	-	Dey.
	(000 0.4)	ventical	φΥ-		70	80	-	
	NTSC Ratio	o(Gamut)			-	60	-	%

#### 6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)



Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

#### 6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Eldim or Equivalent		
3mm//1mm		
Active Area centre point		
A: All Pixels white		
B: All Pixel black		
Maximum		

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

#### 6.4. Definition of Viewing Angles



Measuring machine: LCD-5100 or EQUI

#### 6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



#### 6.6. Definition of Surface Luminance, Uniformity and Transmittance

Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1. Surface Luminance: L<sub>V</sub> = average (L<sub>P1</sub>:L<sub>P9</sub>)
- 6.6.2. Uniformity = Minimal (LP1:LP9) / Maximal (LP1:LP9) \* 100%
- 6.6.3. Transmittance =  $L_V$  on LCD /  $L_V$  on Backlight \* 100%

Note: Measuring machine: BM-7





## 7. Block Diagram and Power Supply

## 8. Interface Pins Definition

No.	Symbol	Function	Remark
1-2	LED_K	LED cathode	
3-4	LED_A	LED anode	
5-7	NC	No connect	
8	RESET	Reset signal, Low active	
9	/CS	Chip select	
10	SCK	SPI Serial Clock	
11	SDI	SPI Serial Data Input/output	
12	B0	Data bus	
13	B1	Data bus	
14	B2	Data bus	
15	B3	Data bus	
16	B4	Data bus	
17	B5	Data bus	
18	B6	Data bus	
19	B7	Data bus	
20	G0	Data bus	
21	G1	Data bus	
22	G2	Data bus	
23	G3	Data bus	
24	G4	Data bus	
25	G5	Data bus	
26	G6	Data bus	
27	G7	Data bus	
28	R0	Data bus	
29	R1	Data bus	
30	R2	Data bus	
31	R3	Data bus	
32	R4	Data bus	
33	R5	Data bus	
34	R6	Data bus	
35	R7	Data bus	
36	HSYNC	Horizontal Synchronous Signal	
37	VSYNC	Vertical Synchronous Signal	
38	DOTCLK	Data Clock	
39-40	NC	No connect	
41-42	VDD	Power Supply	
43-51	NC	No connect	
52	DEN	Data enabling signal	
53-54	GND	Ground	

## 9. AC Characteristics

#### 9.1. AC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit	Conditions
VDD Power Source Slew Time	TPOR	-	-	20	ms	From 0V to 99% VDD
GRB Pulse Width	tRSTW	10	50	-	US	R=10Kohm, C=1uF
SD Output Stable Time	Tst	-	-	12	us	Output settled within +20mV Loading = 6.8k+28.2pF.
GD Output Rise and Fall Time	Tgst	-	-	6	us	Output settled (5%~95%) Loading = 4.7k+29.8pF

#### 9.2. Timing for I2C Interface



ltem	Symbol	Min.	Тур.	Max.	Unit	Conditions
SCL Clock Frequency	FSCL	-		400	KHz	
SCL Clock Low Period	TLOW	1300	a.	-	ns	
SCL Clock High Period	THIGH	600	-		ns	
Signal Rise Time	Tr	20+0.1Cb	÷	300	ns	
Signal Fall Time	Tf	20+0.1Cb	2	300	ns	
Start Condition Setup Time	TSU;STA	600	2	- <u>1</u> 21	ns	
Start Condition Hold Time	THD;STA	600	ě.	8	ns	
Data Setup Time	TSU;DAT	100	2	-	ns	
Data Hold Time	THD;DAT	0		900	ns	
Setup Time for STOP Condition	TSU;STO	600	a.	-	ns	
Bus Free Time Between a STOP and START	TBUF	100	÷	-	ns	
Capacitive load represented by each bus line	Сь	÷	-	400	pF	
Tolerable Spike Width on Bus	TSW	2	<u>.</u>	50	ns	

#### 9.3. Timing for 3-wire SPI Interface



Item	Symbol	Min.	Тур.	Max.	Unit	Conditions
CS Input Setup Time	Ts0	50		-	ns	
Serial Data Input Setup Time	Ts1	50		-	ns	
CS Input Hold Time	Th0	50	- 40	-	ns	
Serial Data Input Hold Time	Th1	50	20 	-	ns	
SCL Write Pulse High Width	Twh1	50	1	-	ns	
SCL Write Pulse Low Width	Twl1	50	-	-	ns	
SCL Read Pulse High Width	Trh1	300			ns	
SCL Read Pulse Low Width	Trl1	300			ns	
CS Pulse High Width	Tw2	400			ns	

#### 9.4. Timing for RGB Interface





Item	Symbol	Min.	Тур.	Max.	Unit	Conditions
CLK Pulse Duty	Tclk	40	50	60	%	
HSYNC Width	Thw	2	-	140	DCLK	
VSYNC Setup Time	Tvst	12	-	( <u>1</u> )	ns	
VSYNC Hold Time	Tvhd	12	-	( <u>1</u> )	ns	
HSYNC Setup Time	Thst	12	-	-	ns	
HSYNC Hold Time	Thhd	12	-	1.71	ns	
Data Setup Time	Tdsu	12		8.58	ns	
Data Hold Time	Tdhd	12		8.75	ns	
DE Setup Time	Tdest	12	-		ns	
DE Hold Time	Tdehd	12		840	ns	

#### 10. Quality Assurance

#### 10.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

#### 10.2. Standard for Quality Test

- 10.2.1. Sampling Plan:
  - GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5.

Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

#### 10.3.Nonconforming Analysis & Disposition

- 10.3.1. Nonconforming analysis:
  - 10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.
  - 10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
  - 10.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.
- 10.3.2. Disposition of nonconforming:
  - 10.3.2.1. Non-conforming product over PPM level will be replaced.
  - 10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

#### 10.4.Agreement Items

Shall negotiate with customer if the following situation occurs:

- 10.4.1. There is any discrepancy in standard of quality assurance.
- 10.4.2. Additional requirement to be added in product specification.
- 10.4.3. Any other special problem.

#### 10.5. Standard of the Product Visual Inspection

- 10.5.1. Appearance inspection:
  - 10.5.1.1. The inspection must be under illumination about 1000 1500 k, and the distance of view must be at 30cm ± 2cm.
  - 10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,



10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.10.5.2.2. New item must be added on time when it is necessary.

#### 10.6.Inspection Specification

No.	ltem	Criteria (Unit: mm)						
	Black / White spot	a	Size	Area	Acc. Qty			
	Foreign material		φ	≤0.10	Ignore			
	(Round type)		0.10	< <b>φ</b> ≤0.15	2			
01	Pinholes	b	0.15	< <b>φ</b> ≤0.25	1			
	Stain		0.1	25< <b>φ</b>	0			
	Particles inside cell.			otal	2 no include			
	(Minor defect)	<b>φ</b> = ( a + b) /2		otai	<b>φ</b> ≤ 0.10			
		Distance between 2	defects should mor	e than 3mm a	apart.			
			Display Area	Total				
		Bright dot	0	0	Natad			
		Dark dot	N≤2	N≤2	Note1			
02	Electrical Defect	Total dot	N≤2	N≤2				
02	(Minor defect)	Mura	Not visible thro	ugh 5% ND fi	Iter. Note 2			
		Remark: 1. Bright dot cause	d by scratch and fo	preign object a	accords to item 1.			

03	Black and White line Scratch Foreign material (Line type) (Minor defect)	F	Length I $L \leq 2.5$	Width W $\leq 0.03$ 0.03 < W $\leq 0.05$	Acc. Qty gnore 3	
			L ≦ 2.5	$0.05 < W \le 0.10$ 0.1 < W	2 0	
			1	Total	3	
				e defects should more thar e back of the display are a		Scratches no
04	Glass Crack (Minor defect)	Crac	k is potential to	enlarge, any type is not a	llowed.	
	Class Chipping Dad					

	Glass Chipping Pad Area: (Minor defect)	
		Length and Width Acc. Qty
		c > 3.0, b< 1.0 1
05		c< 3.0, b< 1.0 3
		a <glass td="" thickness<=""></glass>
	b the c	
	~ a	

#### Rev:1.1

	Glass Chipping Rear of Pad Area:		
	(Minor defect)	Length and Width	Acc. Qty
		c > 3.0, b< 1.0	1
06		c< 3.0, b< 1.0	2
		c< 3.0, b< 0.5	4
	C C	a <glass td="" thicl<=""><td>kness</td></glass>	kness
	b- g		
	Glass Chipping Except Pad Area: (Minor defect)		
		Length and Width	Acc. Qty
07		c > 3.0, b< 1.0	1
07		c< 3.0, b< 1.0	2
		c< 3.0, b< 0.5	4
		a <glass td="" thicl<=""><td>kness</td></glass>	kness
	Glass Corner Chipping: (Minor defect)		
		Length and Width c < 3.0, b< 3.0	Acc. Qty
08		a <glass td="" thick<=""><td>Ignore</td></glass>	Ignore
	b a c		
	Glass Burr:		
	(Minor defect)	Length	Acc. Qty
		F < 1.0	lgnore
09		Glass burr don't affect as dimension.	semble and module

1						
10	FPC Defect: (Minor defect)		10.1 Dent, pinhole v (w: circuitry width.) 10.2 Open circuit is 10.3 No oxidation, c	unacceptable.	nd distortion.	
11	Bubble on Polarizer (Minor defect)		Diameter φ≤0.20 0.20 <φ≤0.30 0.30 <φ≤0.50 0.50 < φ	Acc. Qty Ignore 4 1 None		
12	Dent on Polarizer (Minor defect)		Diameter φ≤0.20 0.20 <φ≤0.30 0.30 <φ≤0.50 0.50 < φ	Acc. Qty Ignore 4 1 None		
13	Bezel		ortion on the Bezel. ngerprints, stains or othe	er contaminatior	٦.	
14	PCB	<ul> <li>14.1 No distortion or contamination on PCB terminals.</li> <li>14.2 All components on PCB must same as documented on the BOM/component layout.</li> <li>14.3 Follow IPC-A-600F.</li> </ul>				
15	Soldering	Follow IPC-A-610	C standard			
16	Electrical Defect (Major defect)	<ul> <li>The below defects must be rejected.</li> <li>16.1 Missing vertical / horizontal segment,</li> <li>16.2 Abnormal Display.</li> <li>16.3 No function or no display.</li> <li>16.4 Current exceeds product specifications.</li> <li>16.5 LCD viewing angle defect.</li> <li>16.6 No Backlight.</li> <li>16.7 Dark Backlight.</li> <li>16.8 Touch Panel no function.</li> </ul>				

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

#### 10.7.Classification of Defects

- 10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 10.7.2. Two minor defects are equal to one major in lot sampling inspection.

#### 10.8.Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

#### 10.9.Packing

- 10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 10.9.2. Modules inside package box should have compliant mark.
- 10.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is  $350 \text{ mm} \pm 50 \text{mm}$ .

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is 350mm±50mm.

**Note2:** Mura on display which appears darker / brighter against background brightness on parts of display area.

## **11. Reliability Specification**

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity Storage	50℃, 90%RH, 96Hrs	2	GB/T2423.3 -2016
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	-20℃, 60min~70℃, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	-	GB/T5170.14 -2009
8	Electrical Static Discharge	Air: $\pm$ 4KV 150pF/330 $\Omega$ 5 times	2	GB/T17626.2
		Contact: $\pm$ 2KV 150pF/330 $\Omega$ 5 times	۷	-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	_	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

#### 12. Precautions and Warranty

#### 12.1.Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

#### 12.2. Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

#### 12.3. Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter.

#### 12.4. Metal Pin (Apply to Products with Metal Pins)

- 12.4.1. Pins of LCD and Backlight
  - 12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering
  - 12.4.1.2. Recommended Soldering Conditions
    - Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1
    - Maximum Solder Temperature: 370 °C
    - Maximum Solder Time: 3s at the maximum temperature
    - Recommended Soldering Temp: 350±20 °C

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting



12.4.2. Pins of EL

12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

- 12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.
- 12.4.2.3. Recommended Soldering Conditions
  - Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290 °C

Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

- 12.4.2.4. No horizontal press on the EL leads during soldering.
- 12.4.2.5. 180° bend EL leads three times is not allowed.

#### 12.4.2.6. Solder Wetting



#### 12.5.Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.

#### 12.6.Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

#### 12.7. Limited Warranty

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

## 13. Packaging

TBD